



Tariffario per l'accesso ai servizi 2026 Utenti esterni

Tariffa oraria a fasce		
A: 200 €/h	B: 100 €/h	C: 50 €/h

Description	Value	Documentation Link
Cleanroom Access	A	
<i>Facilities included in cleanroom access:</i>		
Wet Etching Bench (alkaline)		
Wet Etching Bench (acid)		
Nanostructures Synthesis Bench		
Fluorinated Chemicals Bench		
Stylus Profilometer Tencor P10		
Optical Microscopes Nikon		
Ellipsometer Alpha SE Wollam		https://www.jawoollam.com/download/pdfs/alpha-2.0-brochure.pdf
Wafer Cleaver AX420 LatticeGear		https://www.latticegear.com/store/latticeax-420.html
Tape wafer laminator P200 Powatec		https://www.powatec.com/index.php?id=35&L=1
Staff personnel	B	
Electron Beam and Photolithography Area		
EBL ELS-BODEN50F Elionix	A	https://sts-elionix.com/els-boden-50/
Laser Writer DWL66+ Heidelberg	A	https://heidelberg-instruments.com/product/dwl-66/
UV Flood exposure UV-Exp150R Idonus	-	https://www.idonus.com/downloads/idonus_datasheet_UV-EXP-SYS_2021-12-01.pdf
Laser writer LW405A Microtech	C	https://www.microtechweb.com/2d/lw_specs.htm
Mask aligner Double-side NXQ-4006 Neutronix Quintel	C	http://www.bnmfabrika.com/belgeler/neutronix/NXQ4006%20data%20sheet.pdf
2-Photon Polymerization M4DSYSTEM Laser nanoFab	A	https://micronanotech.polito.it/equipment/nano-rapid-prototyping-system-2pp/
Full Lithographic bench in ISO5 (including: spin coater, hotplate, wet bench)	B	

Deposition and Plasma Etching Area (*)		
E-beam evaporator Temescal FC2000 Ferrotec	A	https://temescal.ferrotec.com/wp-content/uploads/sites/9/Ferrotec-TemescalSystems1014.pdf
E-beam evaporator Telemark	B	
ICP-CVD PlasmaPro 100 Oxford Instruments	A	https://plasma.oxinst.com/products/icpcvd/plasmapro-100-icpcvd
Multi-chamber magnetron sputtering CLUSTER KS300C Kenosistec	A	https://www.kenosistec.com/en/sputtering-systems/
Graphene CVD nanoCVD-8g Moorfield	B	https://moorfield.co.uk/products/nanocvd-8g/
Parylene deposition D6 Diener	C	https://www.plasma.com/en/parylene-system-p6/
ALD TFS200 Beneq	A	https://beneq.com/wp-content/uploads/2020/02/beneq-tfs200-a4-brochure.pdf
ALD THEIA D200 ForgeNano	B	https://www.forgenano.com/ald-technology/
LPCVD MiniTytan 1600 Tystar	A	https://tystar.com/en/products/tytan/mini-series
Copper electroplating IKO Classic	C	https://fibrotools.com/ecsi-iko-classic/
ICP-DRIE PlasmaPro 100 Cobra Oxford Instruments	A	https://plasma.oxinst.com/products/icp-etching/plasmapro-100-cobra-icp
RIE Vision 320 Advanced Vacuum	B	http://tstvn.com/wp-content/uploads/2021/07/catalog-Vision-320-RIE-plasmaTherm-1.pdf
Plasma Asher NANO Diener	C	https://www.plasma.com/it/lessicodellatecnologiadelplasma/plasmaasher/
Thermal treatments		
RTP SSI Solaris 150	C	https://www.ssi-rtp.com/solaris-150mm-rtp
Characterization and Metrology Area		
Dual Beam SEM/FIB Quanta3D FEI	A	https://www.microscop.ru/uploads/2007_02_C06F196_1_Quanta_3D_FEG_J.pdf
TEM Tecnai™ G2 Spirit - TWIN/BioTWIN FEI	A	https://www.microscop.ru/uploads/2006_06_tecnai_g2_spirit_pb.pdf
SEM Phenom XL G2 ThermoFisher	B	https://assets.thermofisher.com/TFS-Assets/MSD/Datasheets/phenom-xl-g2-datasheet.pdf
c-AFM NX20 Park Systems	B	https://www.parksystems.com/products/large-sample-afm/park-nx20/overview
Stylus Profilometer Tencor® P17 KLA	C	https://www.kla.com/products/instruments/stylus-profilers/p-17
Optical Microscope DSX1000 Olympus	C	https://www.olympus-ims.com/en/microscope/dsx/

Optical Criostat Attodry800 Attocube	B	https://www.attocube.com/downloads/atto-dry800.pdf
Optical Cryostat Cryostation 100s Montana	B	https://www.montanainstruments.com/products/ca100r1
Optical semi-automatic probe station TS200-SE MPI	A	https://www.mpi-corporation.com/wp-content/uploads/ASTPDF/MPI-TS200-SE-Manual-Probe-System-Data-Sheet.pdf
Wafer Electrical probe station	C	
Back End		
Hot Embossing 510 HE EVG	B	https://www.evgroup.com/products/bonding/permanent-bonding-systems/evg510
Dicing saw DAD 3221 DISCO	C	https://www.disco.co.jp/eg/products/dicer/dad3221.html
Die Bonder FinePlacer Lambda2 FineTech	B	https://finetech.de/products/fineplacer-lambda-2/
Wafer Bonder AWB04 AML	B	https://aml.co.uk/awb-aligner-wafer-bonder/
Chemical Mechanical Polishing POLI500 G&P	B	http://gnptech2.cafe24.com/wp/wp-content/uploads/2014/05/GnP-Brochure-POLI500.pdf
Wire bonder HB16 TPT	C	https://www.tpt.de/wp-content/uploads/00_Media/99_Elemente_und_Platzhalter/Datenbl%C3%A4tter/HB16_Datasheet_2022.pdf
Additive Manufacturing Area		
Microstereolithography process	C	
PolyJet Printing – Objet 30 Stratasys	B	https://www.stratasys.com/it/3d-printers/printer-catalog/objet30-printer/
Polyjet Printing – J35Pro Stratasys	B	https://www.stratasys.com/it/3d-printers/printer-catalog/polyjet/j35-pro-printer/
Sharebot snowwhite	C	
InkJet Printing Jetlab 4 Microfab	C	https://www.microfab.com/assets/cms/uploads/files/jetlab4_specs_mf6.pdf
Plasma Cleanr O ₂ Atto Diener	C	https://www.plasma.com/en/plasmasystems-at-a-glance/
Copper electroplating IKO Classic	C	https://fibrotools.com/ecsi-iko-classic/
Microfluidic test bench	C	
Full prototyping process	B	

(*) Substrates and precious materials not included.